

LL05BT1006L3

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12.5W Surface Mount TVS Bi-Directional For ESD Protection-5.0V

Features

- Protects one I/O or power line .
- Working voltage : 5V.
- Low clamping voltage.
- Low leakage current.
- Ultra low capacitance : 0.5pF.
- Response time is typically < 1ns.
- Provide transient protection:
IEC 61000-4-2 (ESD) $\pm 15\text{KV}$ (Air), $\pm 8\text{KV}$ (Contact)
IEC 61000-4-4 (EFT) 40A (5/50ns)
IEC 61000-4-5 (Lightning) 1A (8/20us)
- We declare that the material of product compliance with RoHS requirements.
- Suffix "-H" indicates Halogen-free parts, ex.LL05BT1006L3-H

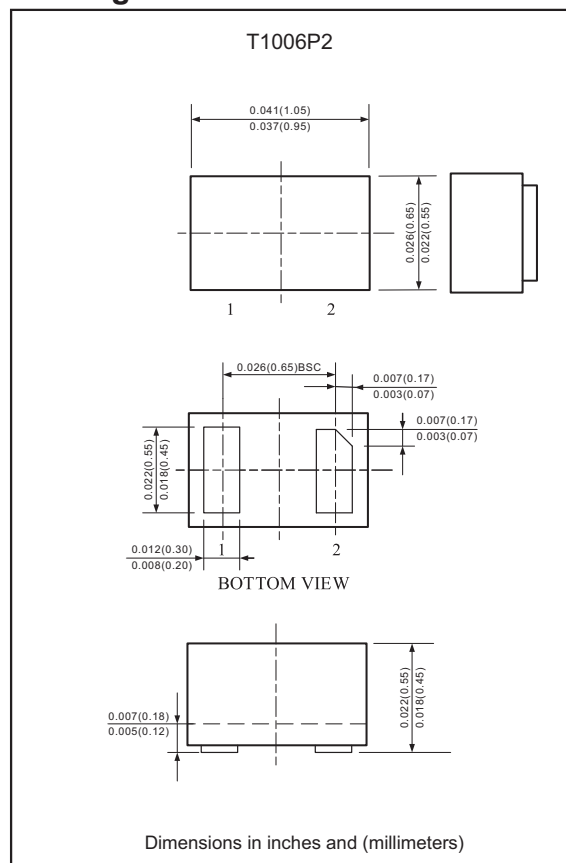
Applications

- Laptop Computers.
- Cellular Phones.
- Digital Cameras.
- Personal Digital Assistants (PDAs).

Mechanical data

- T1006P2 package
- Molding compound flammability rating : UL94V-0
- Packaging : Tape and reel per EIA 481
- RoHS Compliant
- Weight : Approximated 0.73 mg

Package outline



Maximum ratings (at $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak pulse power ($t_p=8/20\mu\text{s}$)	P_{PP}	12.5	W
Peak pulse current ($t_p=8/20\mu\text{s}$)	I_{PP}	1	A
Operating temperature	T_J	+125	$^\circ\text{C}$
Storage temperature	T_{STG}	-55 to +150	$^\circ\text{C}$

Electrical characteristics (at $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Conditions	Symbol	Min.	Typ.	Max.	Unit
Reverse stand-off voltage		V_{RWM}			5.0	V
Breakdown voltage	$I_T=1\text{mA}$	V_{BR}	6.0			V
Reverse leakage current	$V_{RWM}=5\text{V}$	I_R			1	μA
Clamping voltage	$I_{PP}=1\text{A}$, $t_p=8/20\mu\text{s}$	V_C		8.5	12.5	V
Junction capacitance	$V_R=0\text{V}$, $f=1\text{MHz}$	C_j		0.5	0.8	pF

Note : 1.ESD pulse waveform according to IEC 61000-4-2. see Table 1 and Figure 4.
2.ESD tests Setup see Figure 5.

Rating and characteristic curves(LL05BT1006L3)

Figure 1 : Power Derating Curve

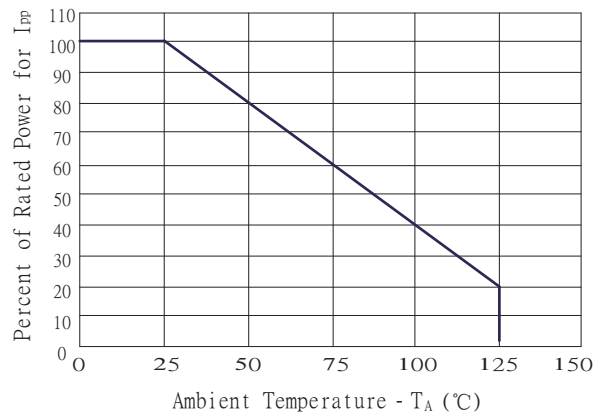


Figure 2 : Insertion Loss

CH S21 LOG 6 dB / REF 0 dB

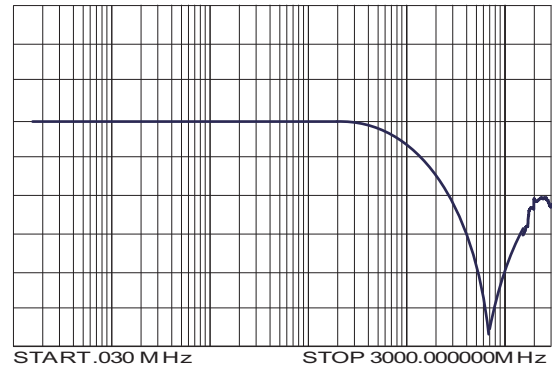


Figure 3 : Normalized Junction Capacitance vs. Reverse Voltage

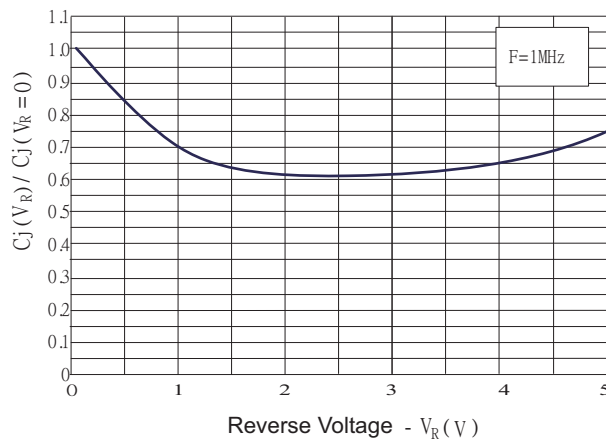


Table 1. IEC 61000-4-2 Discharge Parameters

Level	First Peak Current (A)	Peak Current at 30ns (A)	Peak Current at 60ns (A)	Test Voltage (Contact Discharge) (KV)	Test Voltage (Air Discharge) (KV)
1	7.5	4	2	2	2
2	15	8	4	4	4
3	22.5	12	6	6	8
4	30	16	8	8	15

Figure 4 : IEC61000-4-2 Waveform

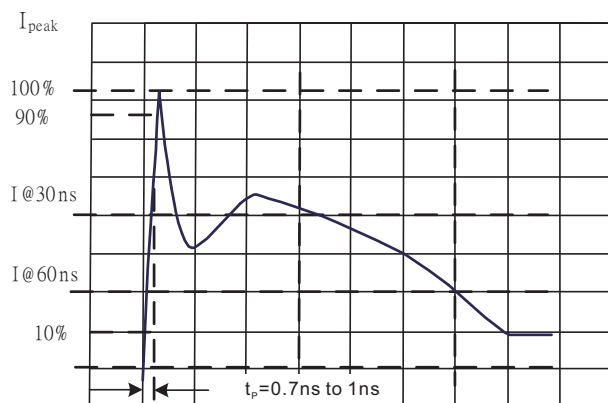
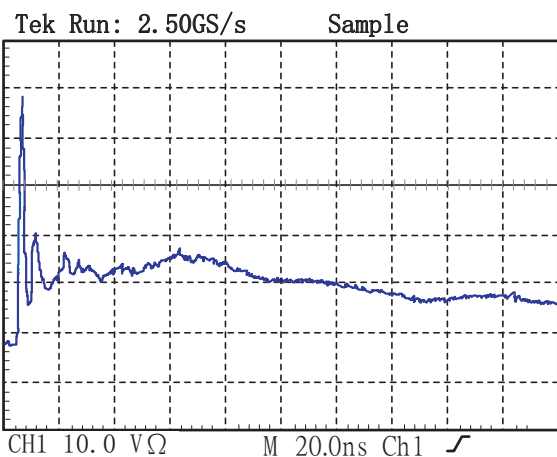
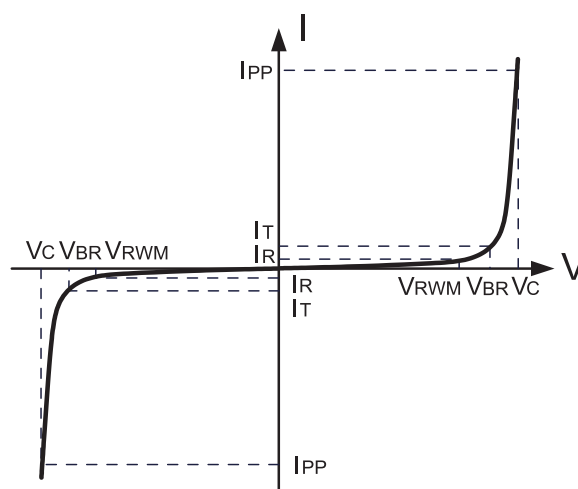


Figure 5 : ESD Clamping (8KV Contact per IEC 61000-4-2)

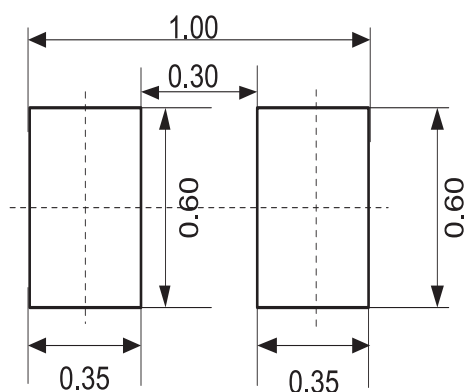


LL05BT1006L3**Electrical Parameters ($T_A=25^{\circ}\text{C}$)**

Symbol	Parameter
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Working Peak Reverse Voltage
I_R	Maximum Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current

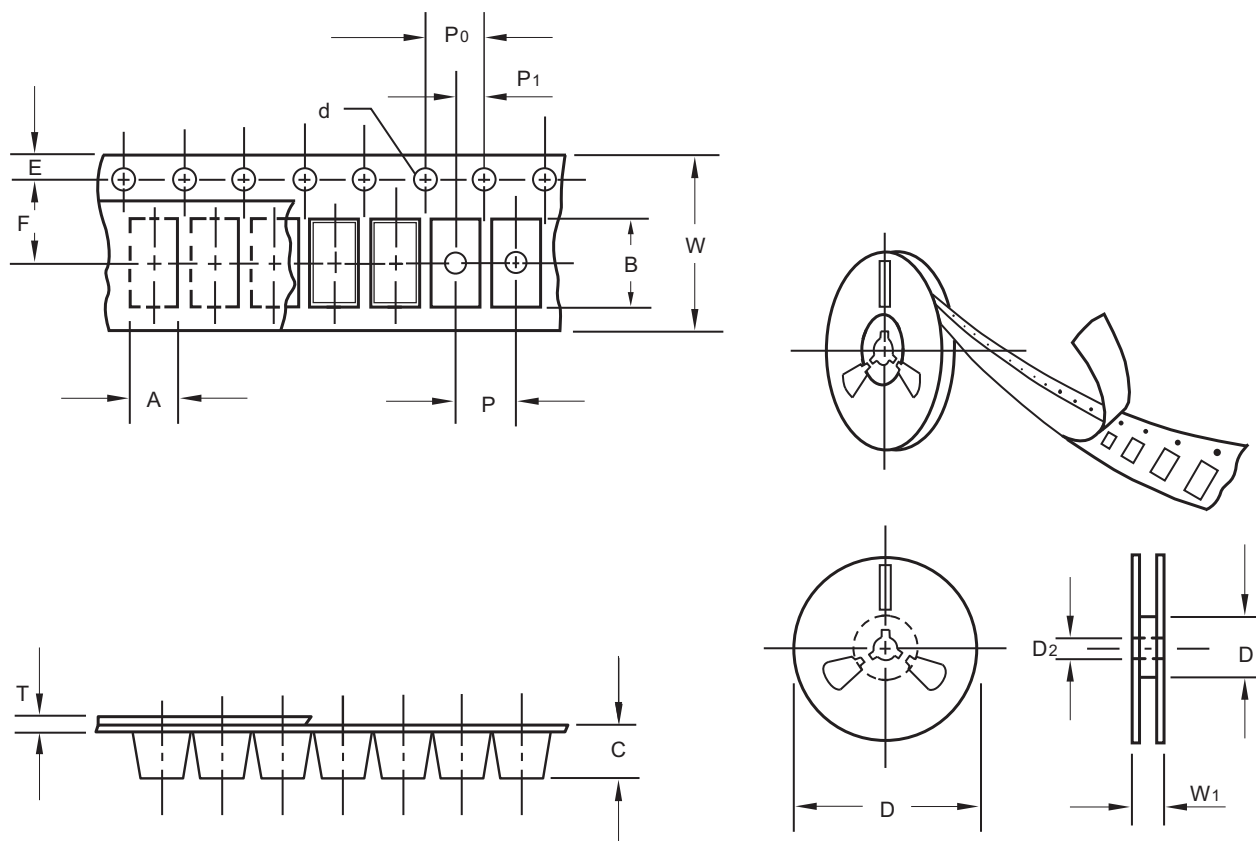
**Pinning information**

Marking Code	Symbol
5T	

Suggested solder pad layout

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Packing information



unit:mm

Item	Symbol	Tolerance	T1006P2
Carrier width	A	0.1	0.66
Carrier length	B	0.1	1.15
Carrier depth	C	0.1	0.66
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	-
13" Reel inner diameter	D1	min	-
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	55.00
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	2.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	8.00
Reel width	W1	1.0	9.50

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

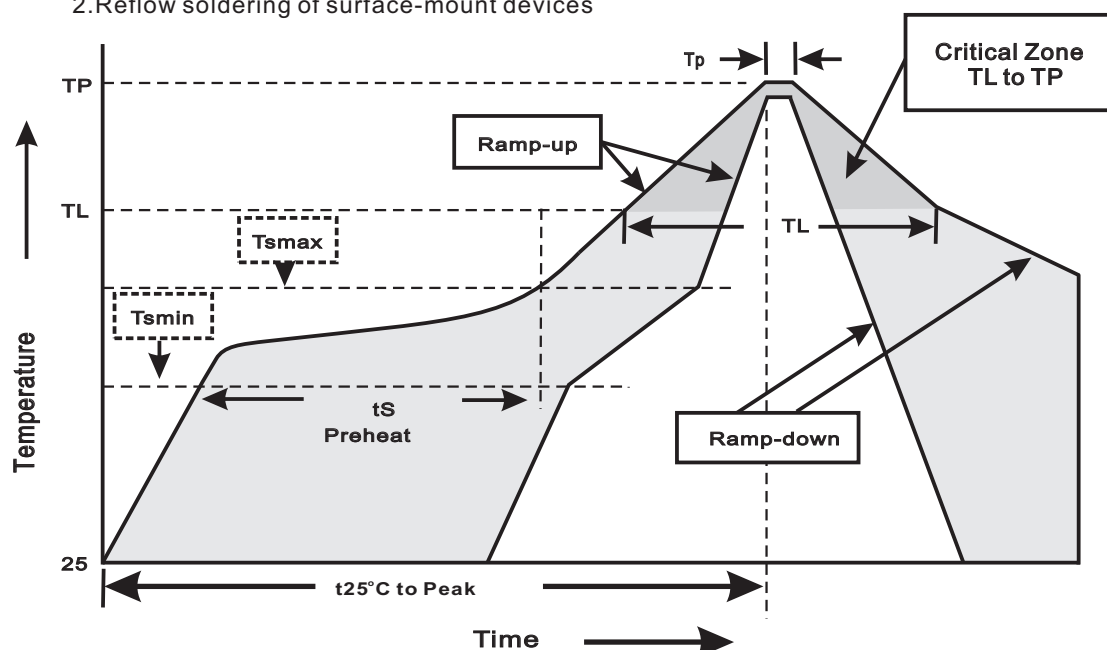
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Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
T1006P2	7"	10,000	4.0	100,000	183*123*183	178	382*257*387	800,000	15.0

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T_L to T_P)	$< 3^\circ\text{C/sec}$
Preheat -Temperature Min(T_{smin}) -Temperature Max(T_{smax}) -Time(min to max)(t_s)	150°C 200°C 60~120sec
T_{smax} to T_L -Ramp-upRate	$< 3^\circ\text{C/sec}$
Time maintained above: -Temperature(T_L) -Time(t_L)	217°C 60~260sec
Peak Temperature(T_P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t_P)	10~30sec
Ramp-down Rate	$< 6^\circ\text{C/sec}$
Time 25°C to Peak Temperature	$< 6\text{minutes}$